

IN THE SPECIFICATION:

Please amend the specification as follows:

Page 3, line 30 to page 4 line 4:

In accordance with a further preferred embodiment of the invention the security element has a second electrically conductive layer, wherein the first and the second electrically conductive layers form a capacitive element in the first surface region. The surface area of the electrically conductive layer in the first surface region is now increased here by the relief structure, thereby increasing the charge density in the first surface region. That then also increases the capacitance of the capacitive element which is provided in the first surface region. That effect can be used to reduce the surface region provided for the capacitive element or to implement fine tuning of the resonance frequency of an oscillator circuit by means of the relief structure. In that way it is possible to increase the packaging density of the security element, reduce production costs and improve the electrical properties of the security element.

Page 5, line 23 to page 6, line 2:

It is further particularly advantageous if the security element represents a film element, in particular a stamping film, a laminating film, a sticker film or a partial element of a transfer layer portion of such a film. The security element can be particularly inexpensively produced in that way. There are also great advantages in regard to later use: the optical security element can thus be applied for example in a particularly and inexpensive manner to security documents such as travel passes, driving licences, entry cards, credit cards, travel cards for transport systems or software licences. That equally applies for the application of the security element to products, for example for safeguarding articles, for tracking articles or for article authentication. It is also possible for the security element to be of a particularly thin and flexible nature.

Page 7, lines 13-20:

The substrate layer 11 is formed by a thin elastic plastic material, for example of a thickness of 20 μm . The conductive layer applied to the top side of the substrate layer 11 is shaped out in pattern form so that it forms an RF antenna coil 12 and a plate of a capacitive element 13. The conductive layer applied to the underside of the substrate layer is also shaped out in pattern form to form an RF component and also forms in the region of the plate 13 a plate [[14]] which together with the plate 13 forms the capacitive element.

Page 18, lines 16-18:

Reference will now be made to Figures 9a to 9b 9d to discuss further possible options in regard to the configuration of a security element for RF identification according to the invention.